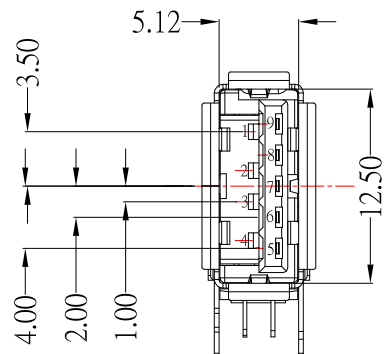
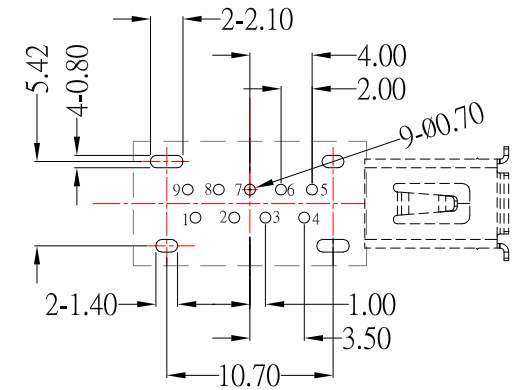


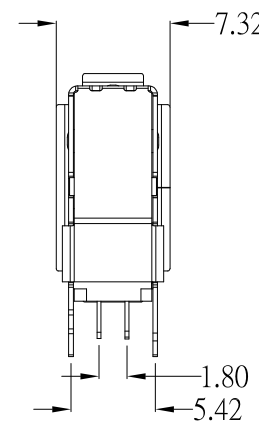
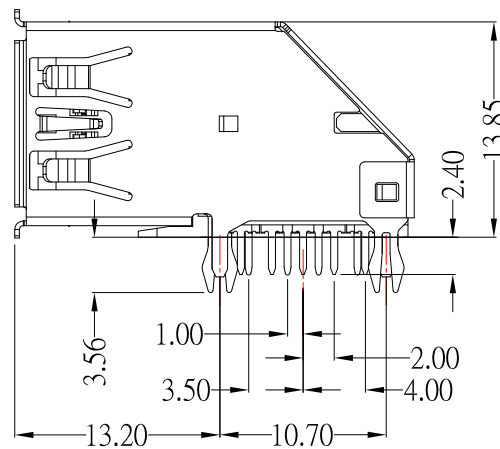
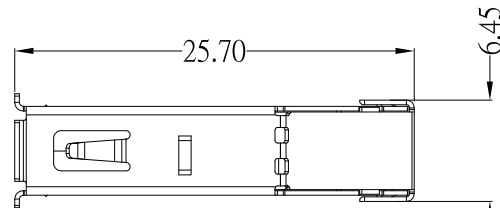
P.C.B LAYOUT MOUNTING PATTERN
(TOP VIEW)



SUA-110P-30x-S277

鍍層厚度:

Blank	: 1u"
2	: 15u"
3	: 30u"



NOTE:

1.MATERIAL:

1.1 HOUSING: PBT , UL 94V-0 , Blue .

1.2 CONTACT: 4PIN-----PHOSPHOR BRONZE.

5PIN-----BRASS.

1.3 SHELL: SUS.

2.Finish:

2.1 CONTACT: PLATED GOLD IN MATING AREA ;
TIN PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL

2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.ELECTRICAL CHARACTERISTICS:

3.1 CONTACT RESISTANCE: 30mΩ MAX (for pin1& pin4),
50mΩ MAX (for other contacts)

3.2 RATING: 1.5 A ,30VDC

3.3 DIELECTRIC WITHSTANDING VOLTAGE: 100 VDC

3.4 INSULATION RESISTANCE 100 MΩ MIN

3.5 OPERATING TEMPERATURE: 0°C ~ 50°C.

4.MECHANICAL CHARACTERISTICS:

4.1 MATING FORCE: 35N MAX;

4.2 UNMATING FORCE: 10N MIN;

4.3 DURABILITY:MANDATORY: 5,000 CYCLES.

ITEM NO.	DESCRIPTION	DRAWN	DATE
4	更新SPEC	Jack	090717
3	新增pin的編號	Jack	090417
2	新增pcb layout中pin的編號	Jack	012715
1	更新SPEC及材質	Jack	010515

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	09/07/17		MODLE	USB AF 3.0 側插
CHECKED BY:	DATE	SCALE	DWG NO.	SIZE
Jacky Chen	09/07/17	1 : 1	SUA-110P-30x-S277	A4
APPROVED BY:	DATE	SHEET NO.	PART NO.	VER
Tony Kao	09/07/17	1 of 1	SUA-110P-30x-S277	R4